

Enhanced Structural Damage Detection Under Thermal Variations Using Finite Element-Based EMI Modeling

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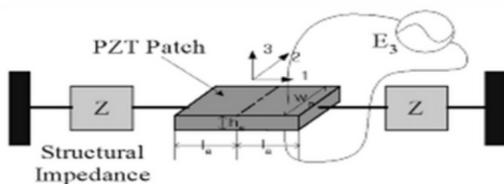
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INTRODUCTION

- EMI-based SHM with bonded PZT sensors is highly sensitive to local stiffness changes (incipient damage).
- In practice, temperature changes material properties and causes frequency and amplitude shifts, generating false alarms.



OBJECTIVES

- Build a 3D FEM EMI model (ANSYS Multiphysics) with temperature-dependent properties.
- Quantify how temperature (25–85°C) and crack depth affect impedance signatures.
- Demonstrate a cross-correlation temperature compensation method to separate temperature effects from true damage.

METHOD

- Model setup :
 - Aluminum beam 500 × 30 × 2 mm
 - PZT patch (PSI-5H4E) 15 × 15 × 0.267 mm, bonded 20 mm from beam end
 - Epoxy layer 0.03 mm
 - Harmonic analysis, high-frequency band around resonance peaks (≈ 18.5–21 kHz)
 - Temperature-dependent properties for beam and PZT
- Damage scenarios : Crack modeled as a 2 mm wide notch, depth varied (2–7 mm), located 125 mm from beam edge.
- Damage metrics : RMSD and CCDM computed using real part of impedance (Re(Z))

RÉSULTATS

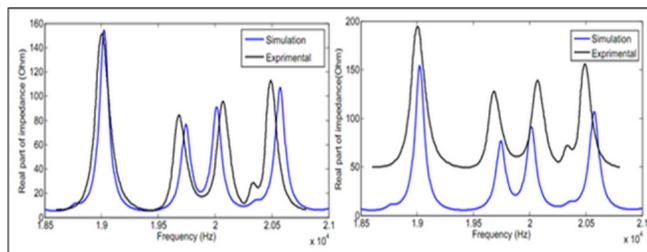
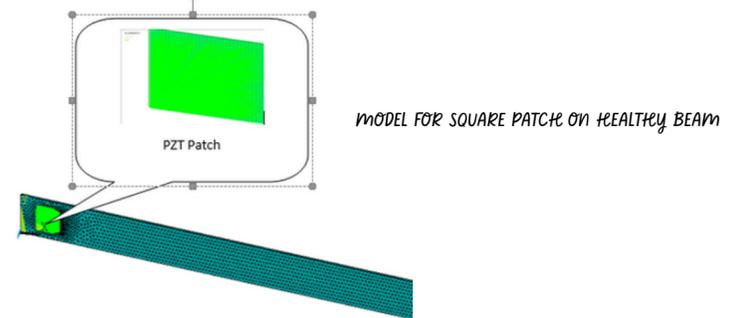
Temperature Effect

- Increase in temperature produces leftward frequency shifts
- Both frequency (horizontal) and amplitude (vertical) changes observed
- Temperature effects may resemble damage signatures

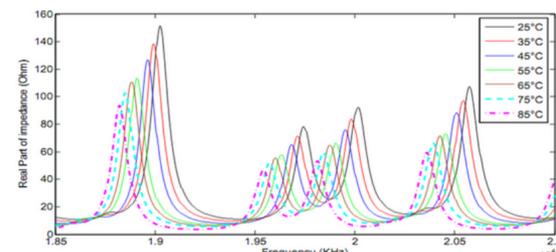
Damage Detection

- Crack growth leads to:
 - Resonance peak shifts
 - Appearance of new peaks
 - Increasing RMSD and CCDM values

EMI technique shows high sensitivity to incipient damage.



COMPARISON BETWEEN SIMULATION AND EXPERIMENTAL RESULT FOR AN ALUMINIUM BEAM (25).



REAL PART OF THE ELECTROMECHANICAL IMPEDANCES RESULTING FROM TEMPERATURE CHANGES

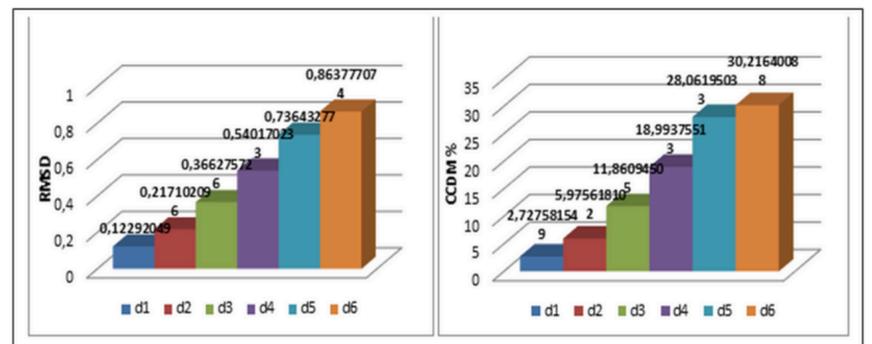
CONCLUSION

- Temperature is a critical environmental factor in EMI-based SHM
- Uncompensated impedance data may lead to misinterpretation
- Proposed approach enables robust, real-time structural monitoring

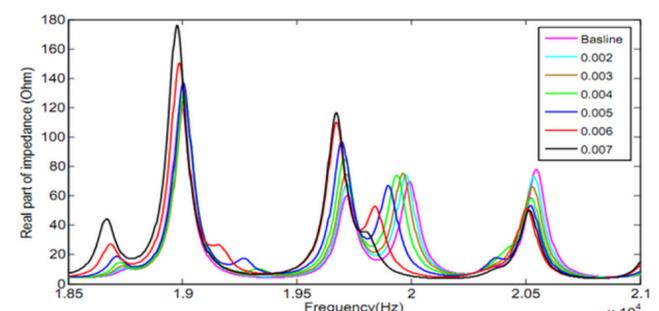
EMI remains a powerful SHM tool when temperature effects are properly addressed.

RÉFÉRENCES

- Liang et al., JIMSS, 1997
Park et al., Shock and Vibration Digest, 2003
Koo et al., JIMSS, 2009



HISTOGRAM OF THE (A) RMSD AND (B) CCDM OF DAMAGE



REAL PART IMPEDANCE FOR DIFFERENT SIZES OF DAMAGE